




<div> MICROCHIP</div>						Package Homogeneous Materials				
Semiconductor Device Type:		V7X	100 TQFP 12x12x1mm Matte Tin							
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	312.02	(mg) Total	Mold Compound	% of Total Weight	79.80
Silica, vitreous (or fused)	60676-86-0	Mold Compound	67.83	265.22	678300		Silica, vitreous (or fused)	60676-86-0	85.00	
Epoxy Resin	Trade Secret	Mold Compound	6.94	27.15	69426		Epoxy Resin	Trade Secret	8.70	
Phenolic Resin	Trade Secret	Mold Compound	4.79	18.72	47880		Phenolic Resin	Trade Secret	6.00	
Carbon Black	1333-86-4	Mold Compound	0.24	0.94	2394		Carbon Black	1333-86-4	0.30	
Copper	7440-50-8	Lead Frame	10.00	39.10	100003		Total		100.00	
Nickel	7440-02-0	Lead Frame	0.27	1.04	2667					
Silver	7440-22-4	Lead Frame	0.18	0.69	1752	41.06	(mg) Total	Lead Frame	% of Total Weight	10.50
Silicon	7440-21-3	Lead Frame	0.05	0.18	473		Copper	7440-50-8	95.24	
Magnesium	7439-95-4	Lead Frame	0.01	0.04	105		Nickel	7440-02-0	2.54	
Silver	7440-22-4	Die Attach	0.56	2.17	5550		Silver	7440-22-4	1.67	
Epoxy resin	68475-94-5	Die Attach	0.17	0.67	1725		Silicon	7440-21-3	0.45	
Copper(II) oxide	1317-38-0	Die Attach	0.02	0.09	225		Magnesium	7439-95-4	0.10	
Silicon	7440-21-3	Die	7.50	29.33	75000		Total		100.00	
Copper	7440-50-8	Bond Wire (CuPdAu Flash Layers)	0.19	0.75	1920					
Palladium	7440-05-3	Bond Wire (CuPdAu Flash Layers)	0.01	0.02	60	2.93	(mg) Total	Die Attach	% of Total Weight	0.75
Gold	7440-57-5	Bond Wire (CuPdAu Flash Layers)	0.00	0.01	20		Silver	7440-22-4	74.00	
Tin	7440-31-5	External Lead Plating	1.25	4.89	12500		Epoxy resin	68475-94-5	23.00	
391.00 mg Total Mass			TOTALS:	100.00	391.00	1,000,000	Copper(II) oxide	1317-38-0	3.00	
						Total		100.00		
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						29.33	(mg) Total	Die	% of Total Weight	7.50
							Silcon	7440-21-3	100.00	
						Total		100.00		
						0.78	(mg) Total	Bond Wire (CuPdAu Flash Layers)	% of Total Weight	0.20
							Copper	7440-50-8	96.00	
							Palladium	7440-05-3	3.00	
							Gold	7440-57-5	1.00	
						Total		100.00		
						4.89	(mg) Total	External Lead Plating	% of Total Weight	1.25
							Tin	7440-31-5	100.00	
						391.00	Total		100.00	100.00

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